

Title (en)

POWER MODULE WITH A CIRCUIT ARRANGEMENT COMPRISING ACTIVE SEMICONDUCTOR COMPONENTS AND PASSIVE COMPONENTS, AND METHOD FOR PRODUCING SAME

Title (de)

LEISTUNGSMODUL MIT EINER AKTIVE HALBLEITERBAUELEMENTE UND PASSIVE BAUELEMENTE AUFWEISENDEN SCHALTUNGSANORDNUNG SOWIE HERSTELLUNGSVERFAHREN HIERZU

Title (fr)

MODULE DE PUISSANCE COMPORTANT UN CIRCUIT POURVU DE COMPOSANTS A SEMICONDUCTEUR ACTIFS ET DE COMPOSANTS PASSIFS, ET SON PROCEDE DE PRODUCTION

Publication

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Application

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Abstract (en)

[origin: DE19700963A1] The invention relates to a power module with a circuit arrangement comprising active semiconductor components and passive components, and a circuit support. At least a part of the active semiconductor components are soldered onto a DCB substrate and at least a part of the passive components is printed onto at least one ceramic support using a thick-film technique. The upper side of the DCB substrate is structured in such a way that it forms conductor strips and contact pads for receiving the active semiconductor components and the passive components of the circuit arrangement. On the ceramic support, for each passive component is printed, using a thick-film technique, a first printed layer and at least one contact area as second printed layer laterally adjoining the first printed layer. The ceramic supports for the passive components printed by thick-film technique are connected via the at least one contact area with the corresponding contact pad(s) of the DCB substrate by a soldering joint.

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